

HAT2285WP

Silicon N Channel Power MOS FET with Schottky Barrier Diode
High Speed Power Switching

REJ03G1371-0300

Rev.3.00

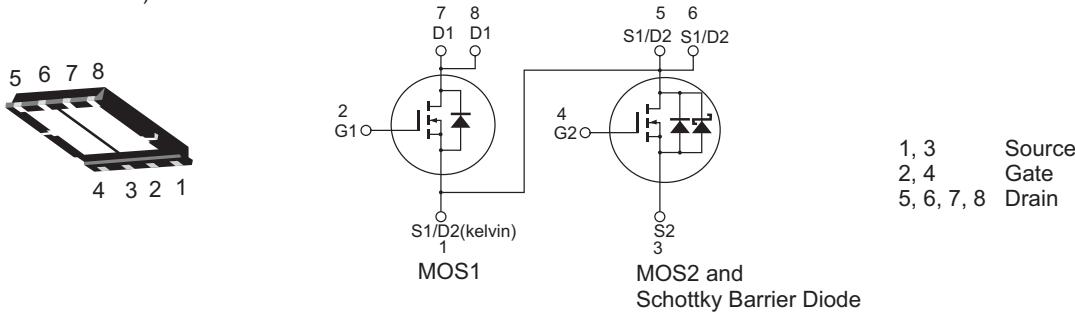
Apr 05, 2006

Features

- Low on-resistance
- Capable of 4.5 V gate drive
- High density mounting
- Built-in Schottky Barrier Diode

Outline

RENESAS Package code: PWSN0008DB-A
(Package name: WPAK-D)



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings		Unit
		MOS1	MOS2 & SBD	
Drain to source voltage	V _{DSS}	30	30	V
Gate to source voltage	V _{GSS}	±20	±12	V
Drain current	I _D	14	22	A
Drain peak current	I _{D(pulse)} ^{Note1}	56	88	A
Reverse drain current	I _{DR}	14	22	A
Channel dissipation	P _{ch} ^{Note2}	8	15	W
Channel temperature	T _{ch}	150	150	°C
Storage temperature	T _{stg}	−55 to +150	−55 to +150	°C

Notes: 1. PW ≤ 10 µs, duty cycle ≤ 1 %

2. T_c = 25°C

Electrical Characteristics

- MOS1

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	30	—	—	V	I _D = 10 mA, V _{GS} = 0
Gate to source leak current	I _{GSS}	—	—	±0.1	μA	V _{GS} = ±20 V, V _{DS} = 0
Zero gate voltage drain current	I _{DSS}	—	—	1	μA	V _{DS} = 30 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	1.0	—	2.5	V	V _{DS} = 10 V, I _D = 1 mA
Static drain to source on state resistance	R _{DS(on)}	—	19	24	mΩ	I _D = 7 A, V _{GS} = 10 V ^{Note3}
	R _{DS(on)}	—	27	40	mΩ	I _D = 7 A, V _{GS} = 4.5 V ^{Note3}
Forward transfer admittance	y _{fs}	10	18	—	S	I _D = 7 A, V _{DS} = 10 V ^{Note3}
Input capacitance	C _{iss}	—	630	—	pF	V _{DS} = 10 V, V _{GS} = 0, f = 1MHz
Output capacitance	C _{oss}	—	155	—	pF	
Reverse transfer capacitance	C _{rss}	—	57	—	pF	
Total gate charge	Q _g	—	4.6	—	nC	V _{DD} = 10 V, V _{GS} = 4.5 V, I _D = 14 A
Gate to source charge	Q _{gs}	—	2.2	—	nC	
Gate to drain charge	Q _{gd}	—	1.2	—	nC	
Turn-on delay time	t _{d(on)}	—	7	—	ns	V _{GS} = 10 V, I _D = 7 A, V _{DD} ≈ 10 V, R _L = 1.42 Ω, R _g = 4.7 Ω
Rise time	t _r	—	30	—	ns	
Turn-off delay time	t _{d(off)}	—	35	—	ns	
Fall time	t _f	—	3.6	—	ns	
Body–drain diode forward voltage	V _{DF}	—	0.91	1.19	V	I _F = 14 A, V _{GS} = 0 ^{Note3}
Body–drain diode reverse recovery time	t _{rr}	—	18	—	ns	I _F = 14 A, V _{GS} = 0 di _F /dt = 100 A/μs

Notes: 3. Pulse test

- MOS2 & Schottky Barrier Diode

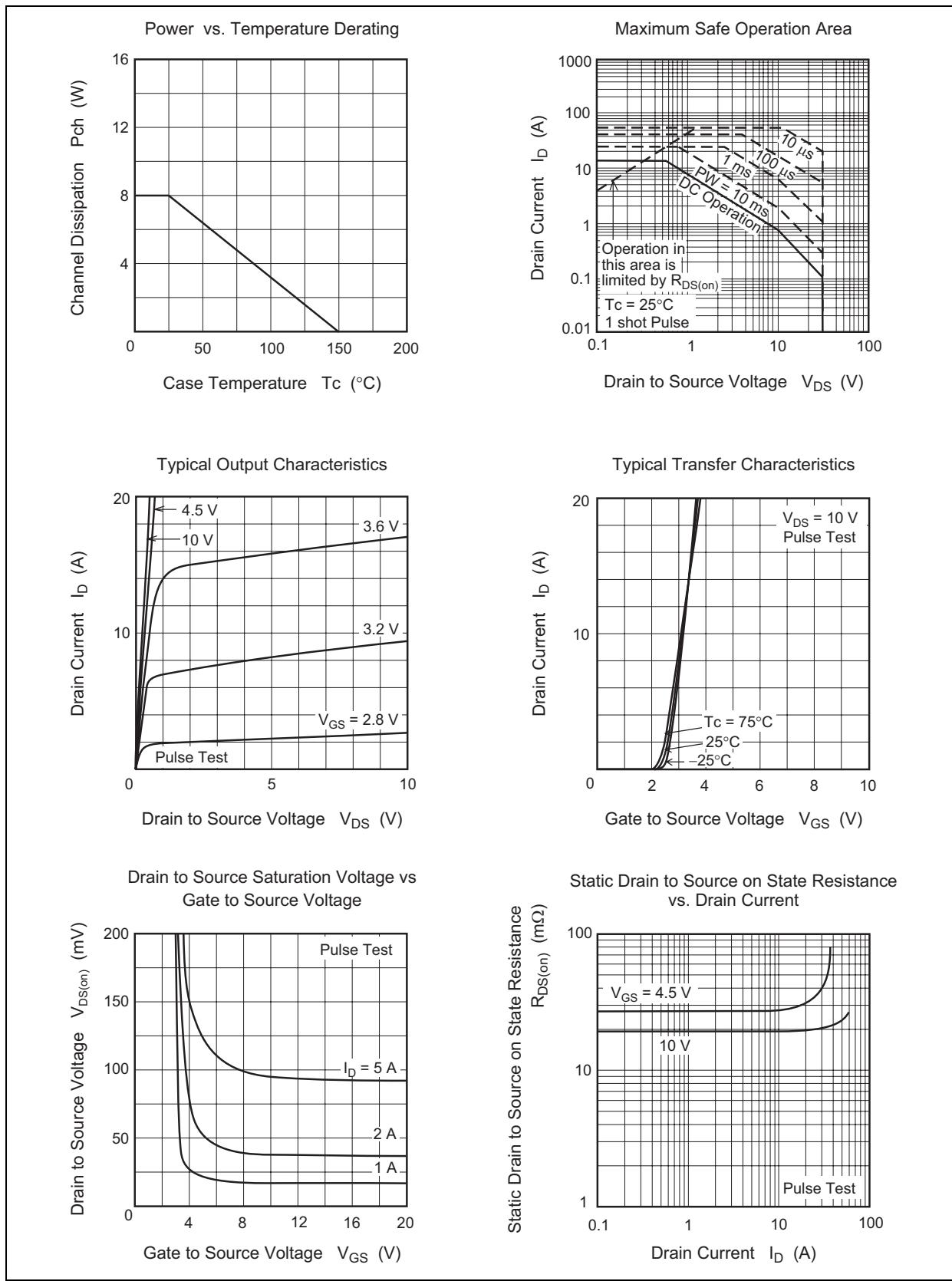
(Ta = 25°C)

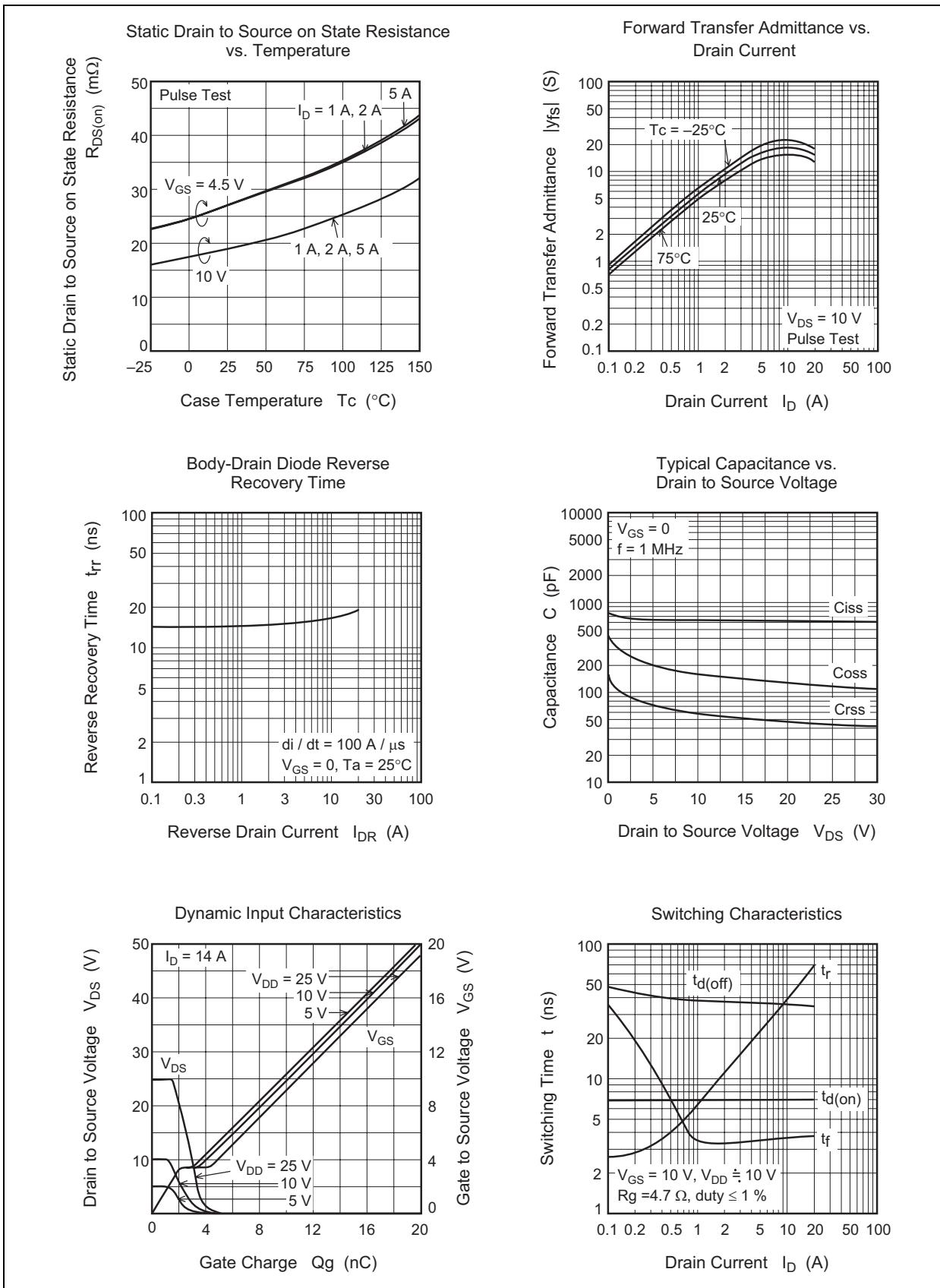
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	V _{(BR)DSS}	30	—	—	V	I _D = 10 mA, V _{GS} = 0
Gate to source leak current	I _{GSS}	—	—	±0.1	μA	V _{GS} = ±12 V, V _{DS} = 0
Zero gate voltage drain current	I _{DSS}	—	—	1	mA	V _{DS} = 30 V, V _{GS} = 0
Gate to source cutoff voltage	V _{GS(off)}	1.4	—	2.5	V	V _{DS} = 10 V, I _D = 1 mA
Static drain to source on state resistance	R _{DS(on)}	—	14	18	mΩ	I _D = 11 A, V _{GS} = 10 V ^{Note3}
	R _{DS(on)}	—	15	23	mΩ	I _D = 11 A, V _{GS} = 4.5 V ^{Note3}
Forward transfer admittance	y _{fs}	24	40	—	S	I _D = 11 A, V _{DS} = 10 V ^{Note3}
Input capacitance	C _{iss}	—	1930	—	pF	V _{DS} = 10 V, V _{GS} = 0, f = 1MHz
Output capacitance	C _{oss}	—	300	—	pF	
Reverse transfer capacitance	C _{rss}	—	130	—	pF	
Total gate charge	Q _g	—	18	—	nC	V _{DD} = 10 V, V _{GS} = 4.5 V, I _D = 22 A
Gate to source charge	Q _{gs}	—	5.8	—	nC	
Gate to drain charge	Q _{gd}	—	4.5	—	nC	
Turn-on delay time	t _{d(on)}	—	10	—	ns	V _{GS} = 10 V, I _D = 11 A, V _{DD} ≈ 10 V, R _L = 0.91 Ω, R _g = 4.7 Ω
Rise time	t _r	—	20	—	ns	
Turn-off delay time	t _{d(off)}	—	45	—	ns	
Fall time	t _f	—	4.0	—	ns	
Schottky Barrier diode forward voltage	V _F	—	0.5	—	V	I _F = 3.5 A, V _{GS} = 0 ^{Note3}
Body–drain diode reverse recovery time	t _{rr}	—	16	—	ns	I _F = 22 A, V _{GS} = 0 di _F /dt = 100 A/μs

Notes: 3. Pulse test

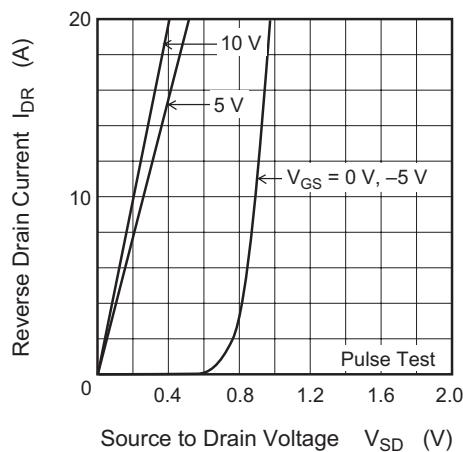
Electrical Characteristics

- MOS1

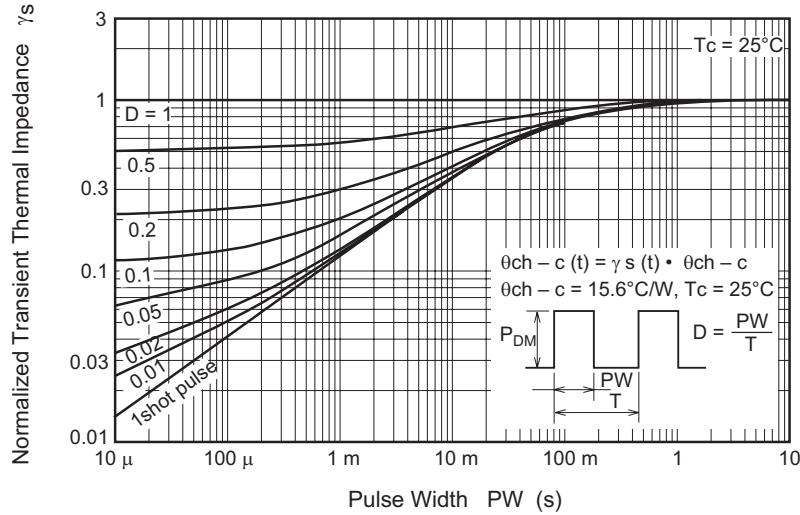




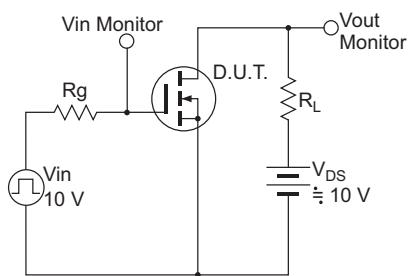
Reverse Drain Current vs.
Source to Drain Voltage



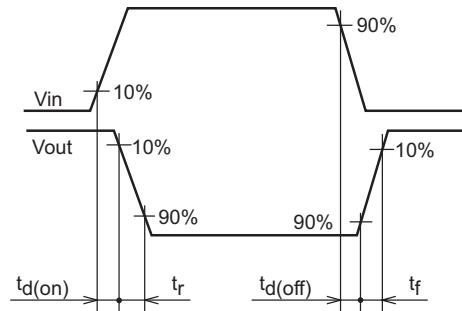
Normalized Transient Thermal Impedance vs. Pulse Width



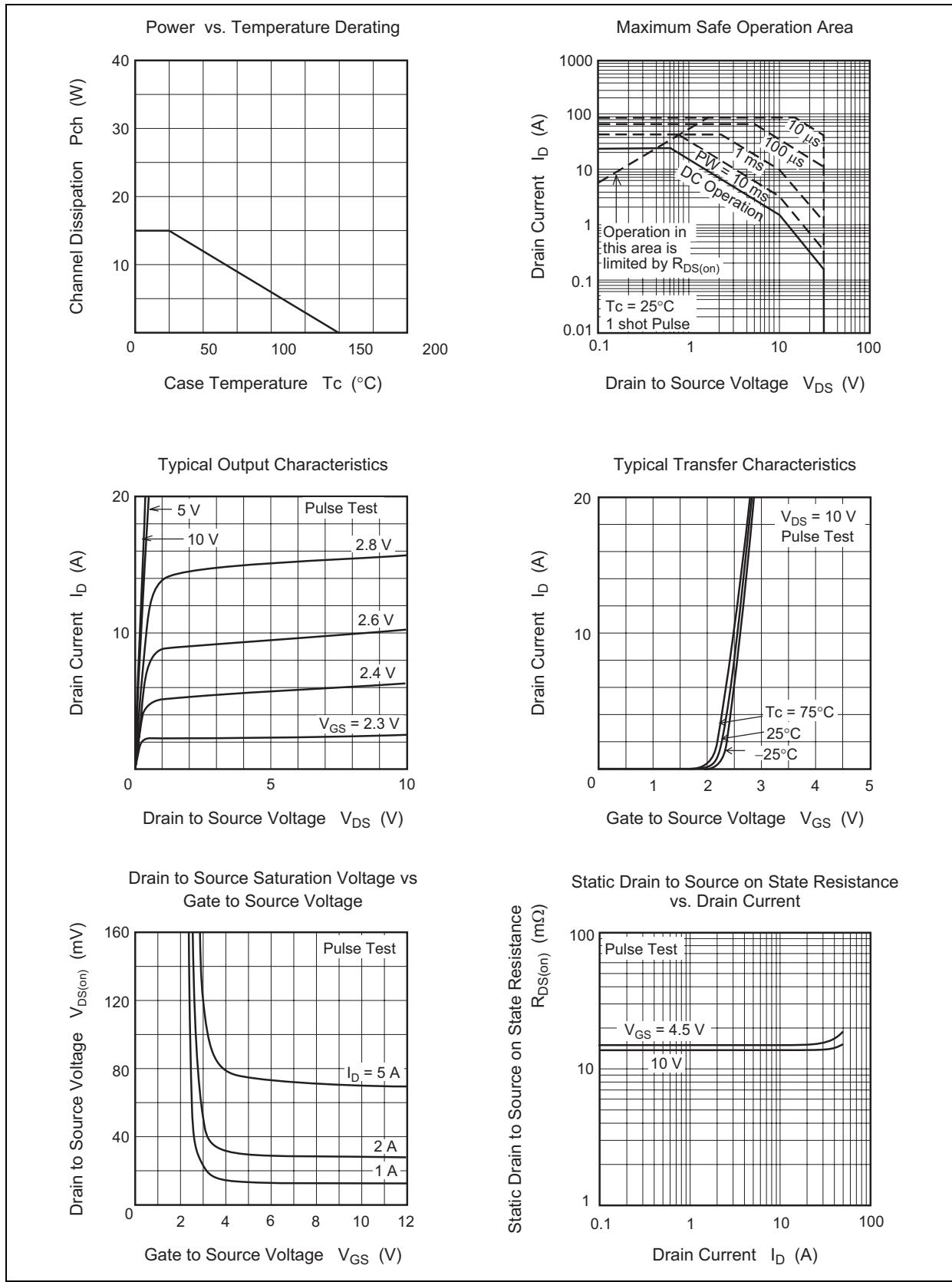
Switching Time Test Circuit

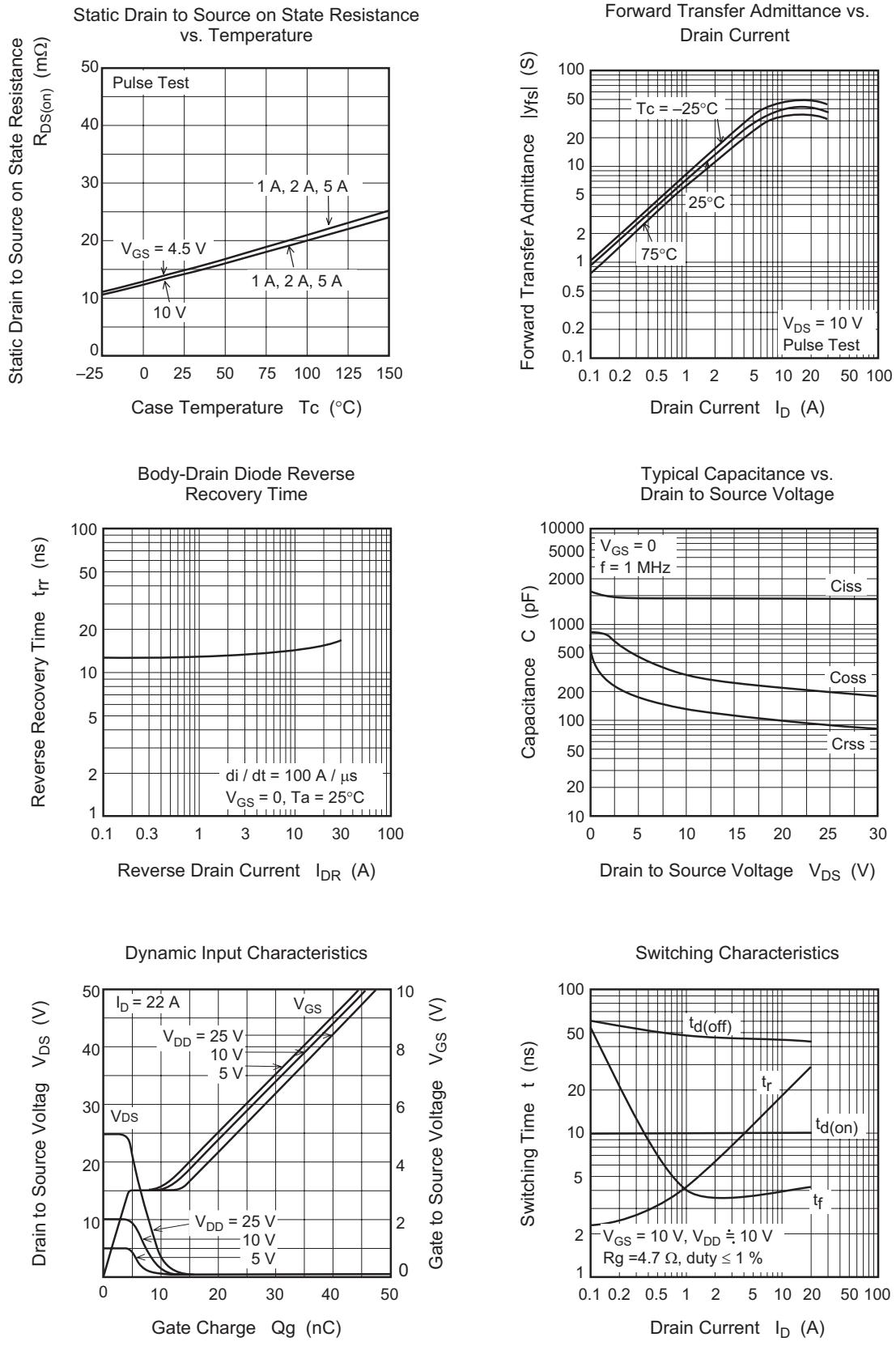


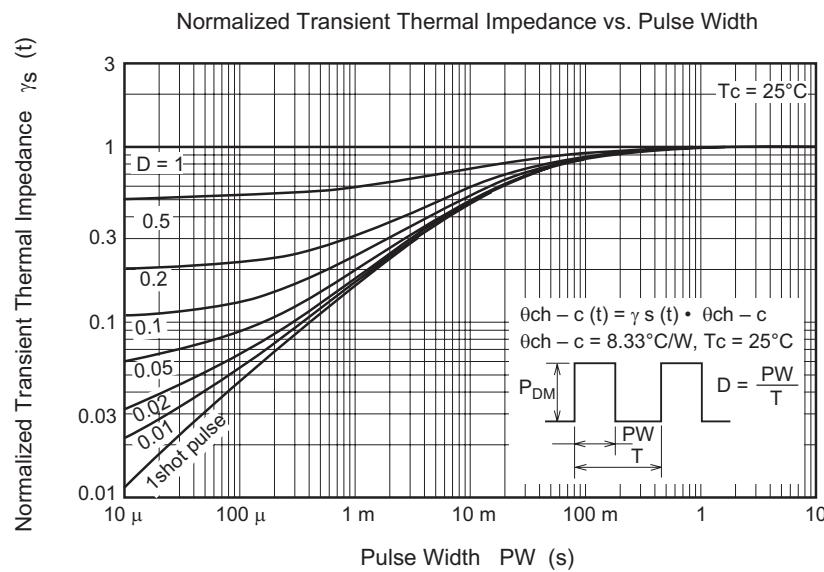
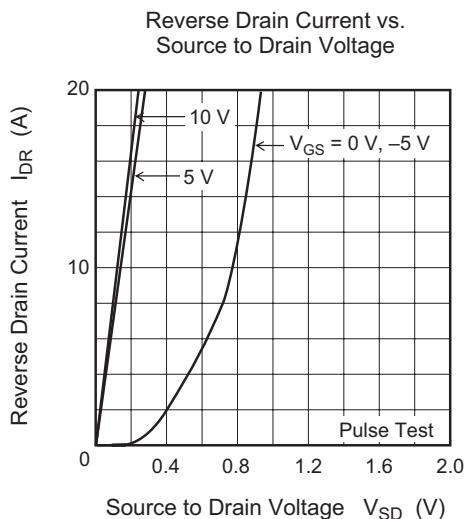
Switching Time Waveform



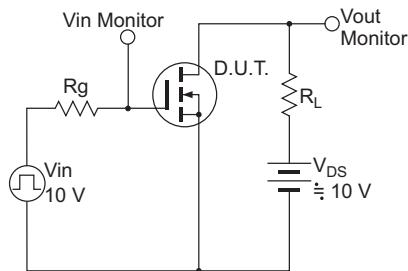
- MOS2 & Schottky Barrier Diode



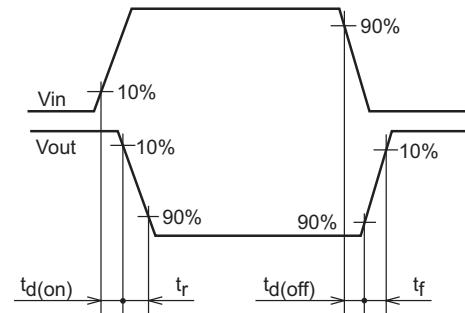




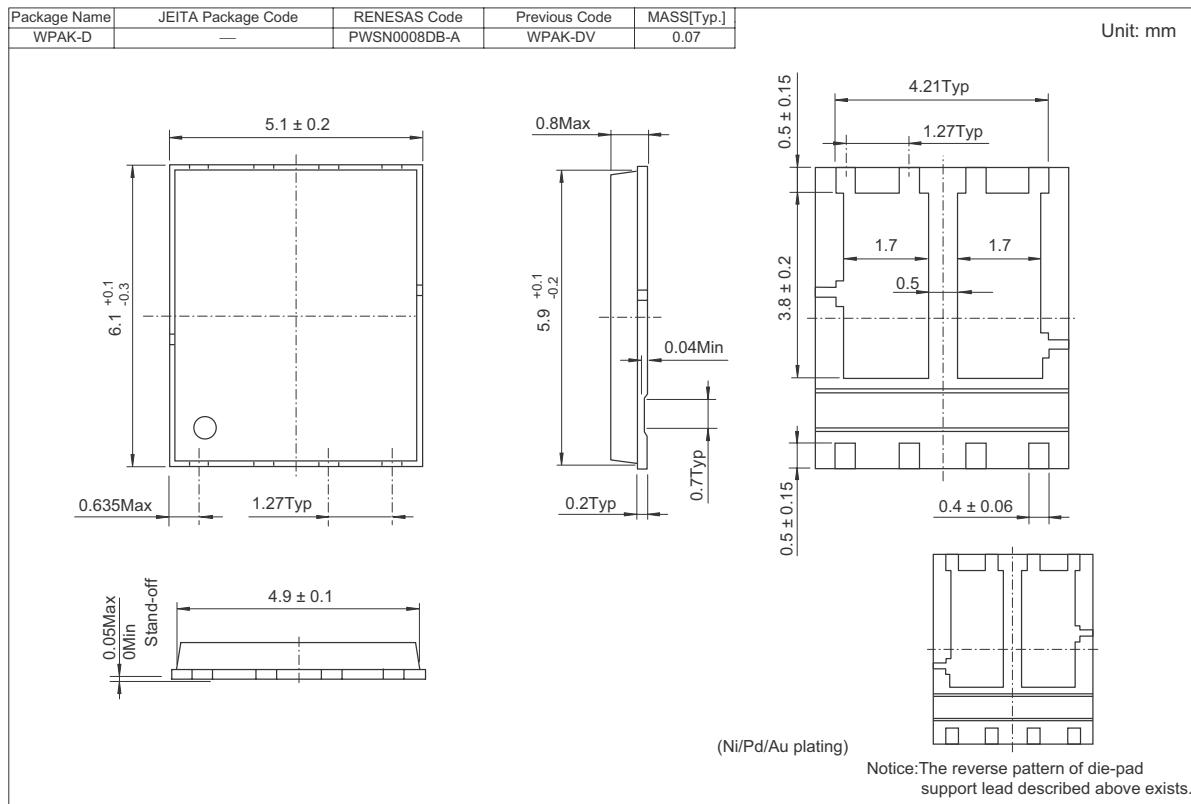
Switching Time Test Circuit



Switching Time Waveform



Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2285WP-EL-E	2500 pcs	Taping

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